L	Hits	Search Text	DB	Time stamp
Number 1	12	(gerald near2 friese).in.	USPAT; US-PGPUB;	2004/03/12 14:19
			EPO; JPO; DERWENT; IBM TDB	14.15
-	2	20020016070.pn.	USPAT; US-PGPUB; EPO; JPO;	2004/03/10 14:45
-	. 4	6159826.pn. or 6239494.pn.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 14:46
_	1987	bond near2 pad same (copper or cu)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 14:47
_ a	60	bond near2 pad same (copper or cu) same probe	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 15:03
-	56	bond\$3 near2 pad same probe same barrier	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 15:07
_	4175	bond\$3 near2 pad near10 structure	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 15:07
_	194	bond\$3 near2 pad near10 structure same probe	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 15:08
-	43	bond\$3 near2 pad near10 structure same probe near2 (region or pad or area)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/10 15:08
-	110	bond\$3 near2 pad near10 structure near20 probe near2 (region or pad or area)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/10 15:08
-	109	bond\$3 near2 pad near10 structure near15 probe near2 (region or pad or area)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/10 15:15
_	3	"03003458"	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 15:15
_	6	"3003458"	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/10 15:16
-	1	6600226.pn.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/10 16:15

Search History

3/12/04 2:21:27 PM

				10004/02/10
-	120	· ·	USPAT;	2004/03/10
		near2 pad	US-PGPUB;	16:15
			EPO; JPO;	
			DERWENT;	
		10.1 10.1	IBM_TDB	2004/03/10
-	31		USPAT;	2004/03/10 16:36
		near2 pad near10 (via or trench or	US-PGPUB;	16:36
		inter\$1connect\$3)	EPO; JPO;	
			DERWENT;	
	-	diffus\$4 near4 barrier near10 bond\$4	IBM_TDB USPAT:	2004/03/10
-	5		US-PGPUB;	16:37
		near2 pad near10 probe	EPO; JPO;	16.37
			DERWENT;	
			IBM TDB	
_	1308	bond\$4 near2 pad near10 probe	USPAT;	2004/03/10
1	1500	Donay i near pad near to prope	US-PGPUB;	16:37
			EPO; JPO;	
-			DERWENT;	
1			IBM TDB	
_	1295	bond\$4 near2 pad near10 probe near2 pad	USPAT;	2004/03/10
			US-PGPUB;	16:38
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	17	bond\$4 near2 pad near10 probe near2 pad	USPAT;	2004/03/10
		near10 etch\$5	US-PGPUB;	16:58
			EPO; JPO;	
			DERWENT;	
	4.5	0.11.1.4.1	IBM_TDB	2004/03/10
-	41	oxide near2 dielectric near4 (boron or	USPAT;	2004/03/10 16:58
		phosphorous) near3 dop\$4	US-PGPUB;	19:28
			EPO; JPO; DERWENT;	
			IBM TDB	
l_	1410	passivat\$4 near2 layer near10 bond\$3	USPAT;	2004/03/11
	1410	near2 pad	US-PGPUB;	13:53
		Hearz pad	EPO; JPO;	13.03
			DERWENT;	
			IBM TDB	
_	380	passivat\$4 near2 layer near10 bond\$3	USPAT;	2004/03/11
		near2 pad near10 etch\$4	US-PGPUB;	13:54
-		-	EPO; JPO;	
			DERWENT;	
	Ì		IBM_TDB	
-	11	passivat\$4 near2 layer near10 bond\$3	USPAT;	2004/03/11
		near2 pad near10 etch\$4 near10 prob\$5	US-PGPUB;	13:56
			EPO; JPO;	
			DERWENT;	
	1025	hander name and name to thinker	IBM_TDB USPAT;	2004/03/11
-	1825	bond\$3 near2 pad near10 thick\$4	US-PGPUB;	13:57
			EPO; JPO;	13.3,
1			DERWENT;	
			IBM TDB	
-	232	bond\$3 near2 pad near10 thick\$4 near10	USPAT;	2004/03/11
	1	(al or aluminum)	US-PGPUB;	13:57
	1	,	EPO; JPO;	
			DERWENT;	
	I		IBM_TDB	
- ';	147		USPĀT;	2004/03/11
4	l 🛊	or aluminum)	US-PGPUB;	13:57
	1 1		EPO; JPO;	
	4		DERWENT;	
] 5			IBM_TDB	2004/02/22
-	55	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/03/11
	*	or aluminum)	US-PGPUB;	13:57
	•		EPO; JPO; DERWENT;	
1			IBM TDB	
	1	<u> </u>	TD11 TDD	<u> </u>

-	4	(al or aluminum) near2 (bond\$3 near2 pad)	USPAT;	2004/03/11
		same (copper or cu) near4 (line)	US-PGPUB;	15:27
			EPO; JPO;	
			DERWENT;	
	5.55	lender	IBM_TDB USPAT;	2004/03/11
-	566	barrier near2 metal near10 (tin titanium	US-PGPUB;	15:28
		or tungsten) near(tan or ta or tantalum)	EPO; JPO;	15.20
			DERWENT;	
			IBM TDB	
	1	barrier near2 metal near10 (tin titanium	USPAT;	2004/03/11
-	1	or tungsten) near2 (tan or ta or	US-PGPUB;	15:29
		tantalum) near10 (bond\$3 near2 pad)	EPO; JPO;	
		cuitarum, marro (sonaro maro pau)	DERWENT;	
			IBM TDB	
_	1	barrier near2 metal near10 (tin titanium	USPĀT;	2004/03/11
	_	or tungsten) near2 (tan or ta or	US-PGPUB;	15:57
		tantalum) near20 (bond\$3 near2 pad)	EPO; JPO;	
1		•	DERWENT;	
			IBM_TDB	
-	1	barrier near2 metal near10 (tin titanium	USPAT;	2004/03/11
		or tungsten) near10 (tan or ta or	US-PGPUB;	15:58
		tantalum) near20 (bond\$3 near2 pad)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/55
-	3	barrier near2 metal near10 (tin titanium	USPAT;	2004/03/11
		or tungsten) near10 (tan or ta or	US-PGPUB;	15:59
		tantalum) near20 pad	EPO; JPO;	
			DERWENT;	
		1	IBM_TDB	2004/03/11
-	828		USPAT; US-PGPUB;	15:59
		or tungsten) near10 (tan or ta or	EPO; JPO;	15:59
		tantalum)	DERWENT;	
			IBM TDB	i
	118	 barrier near2 metal near10 (tin titanium	USPAT;	2004/03/11
_	118	or tungsten) near10 (tan or ta or	US-PGPUB;	16:02
		tantalum) near10 (diffus\$)	EPO; JPO;	20002
		cancalum, meallo (dillusy)	DERWENT;	
			IBM TDB	
_	1	barrier near2 metal near10 (tin titanium	USPAT;	2004/03/11
	_	or tungsten) near10 (tan or ta or	US-PGPUB;	16:03
		tantalum) near10 (diffus\$) and bond\$3	EPO; JPO;	
	1	near2 pad	DERWENT;	
		-	IBM_TDB	
-	6330	dielectric near2 defin\$5	USPAT;	2004/03/11
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	2004/02/11
-	373	dielectric near2 defin\$5 near10 insulat\$4	USPAT;	2004/03/11 16:04
			US-PGPUB;	10:04
			EPO; JPO; DERWENT;	
			IBM TDB	
1_	181	dielectric near2 defin\$5 near10 insulat\$4	USPAT;	2004/03/11
1	181	and @py<2000	US-PGPUB;	16:25
		and epy 2000	EPO; JPO;	
			DERWENT;	
1	1		IBM TDB	
_	10	(copper or cu) near10 metal near2 line	USPAT;	2004/03/11
		near20 bond\$3 near2 pad	US-PGPUB;	16:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	81	(copper or cu) near10 line near20 bond\$3	USPAT;	2004/03/11
		near2 pad	US-PGPUB;	16:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	228	1 1 4 4	USPAT;	2004/03/11
		and bond\$3 near2 pad	US-PGPUB;	16:44
			EPO; JPO;	
Ĭ			DERWENT;	
			IBM TDB	
_	2	5785236.pn.	USPAT;	2004/03/11
	_		US-PGPUB;	17:11
			EPO; JPO;	
			DERWENT;	i l
			IBM_TDB	0004/03/11
-	287		USPAT;	2004/03/11
		near20 bond\$3 near2 pad	US-PGPUB;	17:12
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
_	150	(aluminum or al) near2 interconnect\$4	USPAT;	2004/03/11
ł		near20 bond\$3 near2 pad	US-PGPUB;	17:12
}		nouzzo zona,o nouzz paz	EPO; JPO;	- · ·
			DERWENT;	
		/aluminum on all mann2 interested	IBM_TDB	2004/03/11
-	2		USPAT;	1
		near20 bond\$3 near2 pad near4 (aluminum	US-PGPUB;	17:12
		or al) near20 (copper or cu) near4 line	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
-	113	(aluminum or al) near2 interconnect\$4	USPAT;	2004/03/11
		near20 bond\$3 near2 pad near4 (aluminum	US-PGPUB;	17:13
		or al)	EPO; JPO;	
		or ur,	DERWENT;	
	2410	10 . 5	IBM_TDB	2004/02/11
-	3410	(copper or cu) near10 refract\$4	USPAT;	2004/03/11
ŀ			US-PGPUB;	17:27
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	56	(copper or cu) near10 refract\$4 near5	USPAT;	2004/03/11
		line	US-PGPUB;	17:29
			EPO; JPO;	
			DERWENT;	
	0700		IBM_TDB	2004/03/11
_	2732	, · · ·	USPAT;	2004/03/11
		cu)	US-PGPUB;	17:29
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1 -	1658	conduct\$5 near2 line near10 (copper or	USPAT;	2004/03/11
		cu)	US-PGPUB;	17:29
		/	EPO; JPO;	
			DERWENT;	
	227		IBM_TDB	2004/02/11
-	221	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/03/11
		cu) near10 circuit	US-PGPUB;	17:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	j l
-	5	conduct\$5 near2 line near10 (copper or	USPAT;	2004/03/11
		cu) near10 circuit same bond\$3 near2 pad	US-PGPUB;	17:30
1			EPO; JPO;	
			DERWENT;	
1				
1	136		IBM_TDB	2004/02/11
-	176	l '	USPAT;	2004/03/11
t		near10 circuit and py<2001	US-PGPUB;	17:31
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	101	conduct\$5 near2 line near5 (copper or cu)	USPAT;	2004/03/12
1		near10 circuit and @py<2001	US-PGPUB;	10:28
			EPO; JPO;	
			DERWENT;	
I	[_		IBM_TDB	L

			ucham.	2004/02/12
-	6347	bond near2 pad near5 wire	USPAT; US-PGPUB;	2004/03/12 10:28
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
-	1445	bond near2 pad near5 wire near10 device	USPAT;	2004/03/12
			US-PGPUB;	10:28
			EPO; JPO;	
1			DERWENT; IBM TDB	
_	65	bond near2 pad near5 wire near10 device	USPAT;	2004/03/12
	"	near5 (al or aluminum)	US-PGPUB;	10:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5 1	bond near2 pad near5 wire near10 device	USPAT;	2004/03/12
	. 1	near5 permanent\$5	US-PGPUB;	10:30
]	1 1		EPO; JPO;	
	*		DERWENT;	
	10		IBM_TDB	2004/03/12
-	19	bond near2 pad near5 wire near10 permanent\$5	USPAT; US-PGPUB;	10:35
	T	permanents	EPO; JPO;	10.33
	F		DERWENT;	
			IBM TDB	
l ,	16	bond near2 pad near10 bond near2 wire	USPAT;	2004/03/12
1	3	near10 permanent\$5	US-PGPUB;	10:37
	•	•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	19	l ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2004/03/12
		permanent\$5	US-PGPUB; EPO; JPO;	10:46
			DERWENT;	
			IBM TDB	
_	1621	barrier near2 layer near5 (titanium ti	USPAT;	2004/03/12
		tin) near5 (tantalum or tan or ta)	US-PGPUB;	10:47
			EPO; JPO;	
			DERWENT;	
		<u> </u>	IBM_TDB	0004/00/10
-	0		USPAT;	2004/03/12
		tin) near5 (tantalum or tan or ta) near10	US-PGPUB;	10:47
		bond near2 pad	EPO; JPO; DERWENT;	
			IBM TDB	
_	0	barrier near2 layer near5 (titanium ti	USPAT;	2004/03/12
	1	tin) near5 (tantalum or tan or ta) near20	US-PGPUB;	10:47
		bond near2 pad	EPO; JPO;	
		•	DERWENT;	
			IBM_TDB	
-	52		USPAT;	2004/03/12
1		tin) near5 (tantalum or tan or ta) near5	US-PGPUB;	10:47
		(copper and aluminum)	EPO; JPO;	
			DERWENT; IBM TDB	
			TON TOB	l

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